SDLS004 D2633, JANUARY 1981-REVISED MARCH 1988

- Parallel Register Inputs ('LS592)
- Parallel 3-State I/O: Register Inputs/ Counter Outputs ('LS593)
- Counter has Direct Overriding Load and Clear
- Accurate Counter Frequency: DC to 20 MHz

description

The 'LS592 comes in a 16-pin package and consists of a parallel input, 8-bit storage register feeding an 8-bit binary counter. Both the register and the counter have individual positive-edge-triggered clocks. In addition, the counter has direct load and clear functions. A low-going $\overline{\text{RCO}}$ pulse will be obtained when the counter reaches the hex word FF. Expansion is easily accomplished for two stages by connecting $\overline{\text{RCO}}$ of the first stage to $\overline{\text{CCKEN}}$ of the second stage. Cascading for larger count chains can be accomplished by connecting $\overline{\text{RCO}}$ of each stage to CCK of the following stage.

The 'LS593 comes in a 20-pin package and has all the features of the 'LS592 plus 3-state I/O, which provides parallel counter outputs. The tables below show the operation of the enable (CCKEN, $\overline{\text{CCKEN}}$) inputs. A register clock enable ($\overline{\text{RCKEN}}$) is also provided.

OUTPUT ENABLE CONTROL ('593 ONLY)

G	G	A/Q_A thru H/Q_H
L	L	input mode
L	H	input mode
н	L	output mode
н	н	input mode

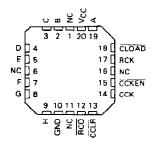
COUNTER CLOCK ENABLE CONTROL

CCKEN	EFFECT ON CCK
L	Enable
н	Disable
L	Enable
н	Enable
	L H L

SN54LS592 ... J OR W PACKAGE SN74LS592 ... N PACKAGE (TOP VIEW)

B [] 1	U16[] Vcc
⊂ [] 2	15] ^
0 🖸 3	14	CLOAD
E [4	13	RCK
F 🗌 5	12	CCKEN
G [6	11] сск
н [7	10	CCLR
	9	RCO

SN54LS592 ... FK PACKAGE (TOP VIEW)



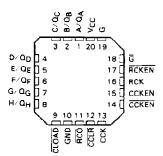
NC - No internal connection

SN54LS593 . . . J OR W PACKAGE SN74LS593 . . . DW OR N PACKAGE (TOP VIFW)

4	UF	AICAAL

A/ QA [B/ QB] C/ QC] D/ QD] E/ QE] F/ QF] H/ QH]	1 2 3 4 5 6 7 8	20 19 18 17 16 15 14 13	Vcc G G RCKEN RCK RCK CCKEN CCKEN CCK
	8 9 10	F	

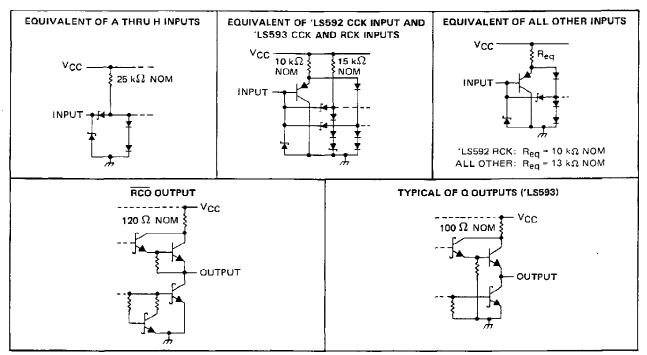
SN54LS593 . . . FK PACKAGE (TOP VIEW)



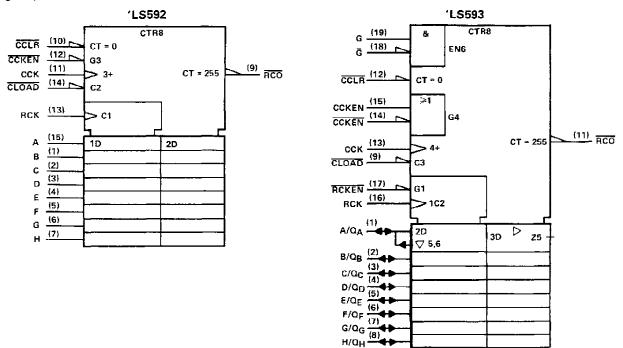
PRODUCTION DATA documents contain information current as of publication data. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does nat necessarily include testing of all parameters.



schematics of inputs and outputs



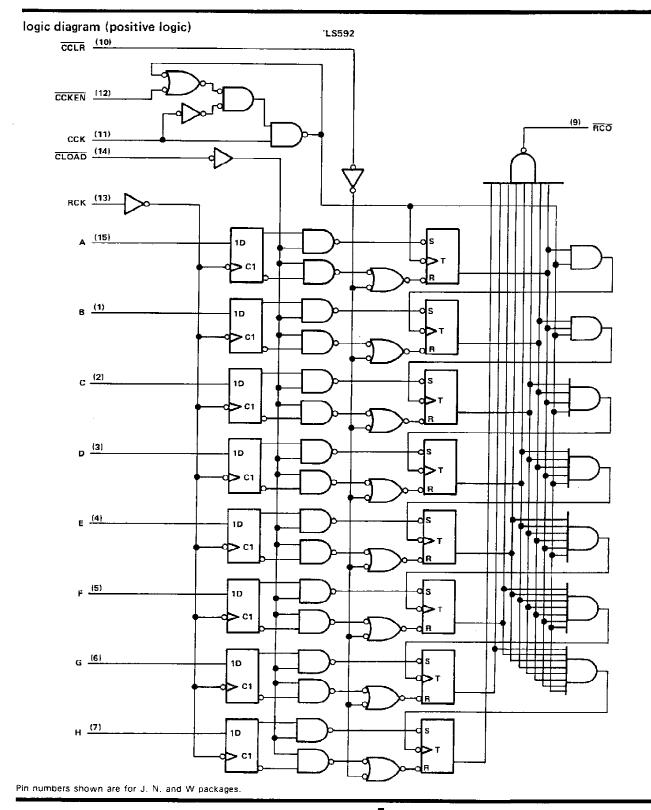
logic symbols t



 † These symbols are in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12. Pin numbers shown are for DW, J, N, and W packages.



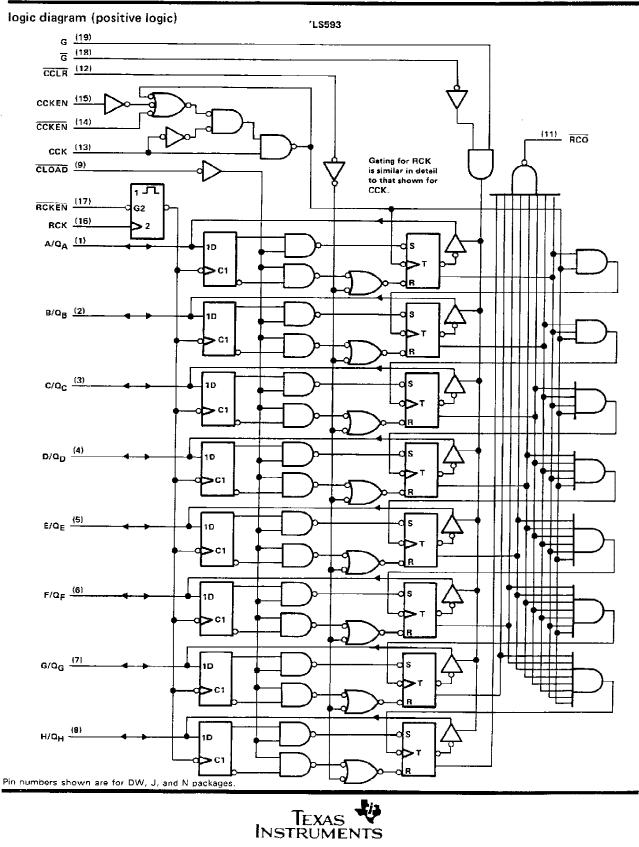
SN54LS592, SN74LS592 8-BIT BINARY COUNTERS WITH INPUT REGISTERS

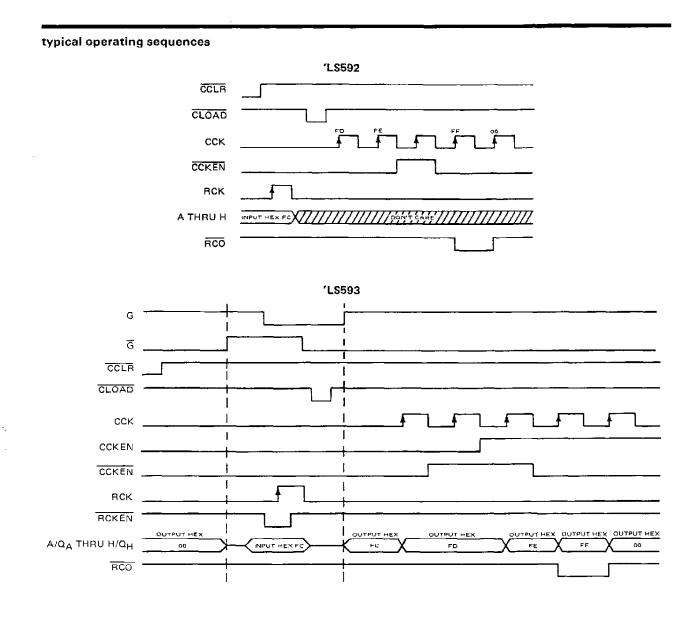


-_



SN54LS593, SN74LS593 **8-BIT BINARY COUNTERS WITH INPUT REGISTERS**







absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)	7 V
Input voltage (excluding I/O ports)	
Off-state output voltage (including I/O ports)	
Operating free-air temperature range: SN54LS592, SN54LS593	55°C to 125°C
SN74LS592, SN74LS593	0°C to 70°C
Storage temperature range	-65° C to 150° C

 $^\circ$ NOTE 1: Voltage values are with respect to the network ground terminal.

recommended operating conditions

				SN54LS	Y .	SN74LS'			UNIT
-			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage		4.5	5	5.5	4.75	5	5.25	V
V _{IH}	High-level input voltage		2			2			v
VIL	Low-level input voltage				0.7			0.8	V
юн	High-level output current	RCO	1		- 1			- 1	
UH	inginever output current	Q'LS593 only			- 1			- 2.6	mA
101	Low-level output current	RCO			8	<u> </u>		16	
		Q 'LS593 only			12			24	mΑ
fcck	Counter clock frequency		0		20	0		20	MHz
t _w (CCK)	Duration of counter clock p	ulse	25			25			ns
tw (CCLR)	Duration of counter clear pu	ilse	20			20			ns
tw (RCK)	Duration of register clock p	lise	20			20			ns
tw CLOAD	Duration of counter load pu	lse	40		• •	40			ns
t _{su}	Register enable setup time	RCKEN low to RCK 1, 'LS593	20			20		-	ns
	Counter enable setup time	CCKEN low, 'LS592	30			30			
t _{su}	before CCK t	CCKEN low or CCKEN high, 'LS593	30			30			715
		CCLR inactive before CCK 1	20			20			
+	Setup time	CLOAD inactive before CCK 1	20			20			
tsu		RCK t before CLOAD t (see Note 2)	30			30			ns
		Data A thru H before RCK 1	20			20			1
th	Hold time	Data A thru H after RCK †	0			0			
····	· · · · · · · · · · · · · · · · · · ·	All others	0			0			ńs
TA	Operating free-air temperatu	re	- 55		125	0		70	°c

NOTE 2: This time insures the data saved by RCK 1 will also be loaded into the counter.



				S	N54LS'		[•	UNIT			
	PARAMETER	TEST CONDITI	MIN	TYP	MAX	X MIN	TYP [‡]	MAX	UNIT		
Viĸ		VCC = MIN, II = -18 m/	4			- 1.5			- 1.5	V	
	'LS593 Q	$V_{CC} = MIN, V_{H} = 2 V,$	l _{OH} = -1 mA	2.4	3.2						
∨он	L3333 Q	$v_{CC} = MAX$	I _{OH} = -2.6 mA				2.4	3.1		V	
	RCO		$I_{OH} = -1 \text{ mA}$	2.4	3.2		2.4	3.2			
	1S593 Q		loL = 12 mA		0.25	0.4		0.25	0.4		
VOL		V_{CC} – MIN, V_{IH} = 2 V,	I _{OL} = 24 mA					0.35	0.5	v	
RCO	V _{IL} = MAX	loL = 8 mA		0.25	0.4		0.25	0.4			
			I _{OL} = 16 mA					0.35	0.5		
^I OZH	'LS593 Q	$V_{CC} = MAX, V_{IH} = 2 V,$ $V_{O} = 2.7 V$	V _{IL} ≖ MAX.			20			20	μA	
^I OZL	'LS593 Q	$V_{CC} = MAX, V_{IH} - 2 V,$ $V_{O} = 0.4 V$	V _{IL} = MAX,			-0.4			-0.4	mA	
	'LS593 Q		VI = 5.5 V			0.1			0.1	mА	
11	Others	V _{CC} - MAX	V ₁ = 7 V			0.1			0.1	mA	
¦ін		$V_{CC} = MAX, V_{I} = 2.7 V$				20			20	μA	
	ССК					-0.8			-0.8		
	RCK LS592					-0.2			- 0.2	1	
hι	101 (LS593	$V_{CC} = MAX, V_I = 0.4 V$				-0.8			- 0.8	mA	
	A thru H					-0.4			-0.4		
	Others					-0.2			-0.2		
los [§]	'LS593 Q	$V_{CC} = MAX, V_0 = 0 V$		- 30		- 130	- 30		- 130	mA	
.03	RCO			- 20		- 100	- 20		- 100		
	'LS592 CCH				40	60		40	60		
	ICCL	$V_{CC} = MAX,$			40	60 70	ļ	40	60		
lcc		,	II possible inputs grounded,					47	70	-	
	'LS593 1 _{CCL}	All outputs open		53	80	ļ	53	80	-		
	l 'ccz				57	85		57	85		

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

¹For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

[‡]All typical values are at V_{CC} = 5 V, T_A = 25 °C.

٦.

Not more than one output should be shorted at a time and the duration of the short-circuit should not exceed one second.



	FROM	то				LS592			'LS593		UNI
PARAMETER	(INPUT)	(OUTPUT)	TEST COND	TIONS	MIN	TYP	MAX	MIN	түр	MAX	
fmax	сск	RCO	$B_L = 1 k\Omega$,	C լ_ = 30 pF	20	35		20	35		MHz
^t PLH	CCK1	Q							14	21	ns
^t PHL	CCK1	Q	R _L = 667 Ω,						26	39	ns
ĩ₽LH	CLOAD +	Q							34	51	ns
tPHL	CLOAD +	Q		CL = 45 pF					28	42	ns
tPHL	CCLR +	a							25	38	ns
^t PZH	Gt	Q							31	47	ns
TPZL	Gt	Q							27	40	រាទ
^t PZH	G↓	۵							29	45	ns
tPZL	G i	٩							31	47	ns
tPHZ	G↓	a		С _ = 5 рF	1				33	50	ns
^t PLZ	Gł	٩				-			35	52	ns
^t PHZ	<u>G</u> t	٩	HL=00/12,						26	39	ns
^t PLZ	Ğt	٩							28	42	ns
¹ PLH	CCK t	RCO				15	23		14	21	ns
^t PHL	CCKT	RCO				20	30		20	30	ns
^t PLH	CLOAD +	RC0	RL=1kΩ,	C _L = 30 pF		31	47		31	47	ns
tPHL	CLOAD 4	RCO				27	41		27	41	ns
t₽LH	CCLR +	RCO				30	45		30	45	пŝ
^t ₽LH	RCK 1	нсо	$R_{L} = 1 k\Omega;$	CL = 30 pF		35	53		42	63	ns
tphL	RCK †	RCD	CLOAD = L			30	45		33	50	ns

switching characteristics, V_{CC} = 5 V, T_A = 25 $^{\circ}$ C, (see note 3)

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.





PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-8762101EA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8762101EA SNJ54LS592J	Samples
5962-8762101FA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8762101FA SNJ54LS592W	Samples
5962-8762101FA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8762101FA SNJ54LS592W	Samples
SN54LS592J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS592J	Samples
SN54LS592J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS592J	Samples
SN54LS593J	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS593J	Samples
SN54LS593J	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS593J	Samples
SN74LS592D	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS592	Samples
SN74LS592D	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	L\$592	Samples
SN74LS592N	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS592N	Samples
SN74LS592N	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS592N	Samples
SN74LS592NSR	ACTIVE	SO	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS592	Samples
SN74LS592NSR	ACTIVE	SO	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS592	Samples
SN74LS593DW	ACTIVE	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS593	Samples
SN74LS593DW	ACTIVE	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS593	Samples
SN74LS593DWR	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS593	Samples
SN74LS593DWR	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS593	Samples
SN74LS593N	ACTIVE	PDIP	N	20	20	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS593N	Samples

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Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LS593N	ACTIVE	PDIP	N	20	20	RoHS & Green	(6) NIPDAU	N / A for Pkg Type	0 to 70	SN74LS593N	Samples
SNJ54LS592J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8762101EA SNJ54LS592J	Samples
SNJ54LS592J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8762101EA SNJ54LS592J	Samples
SNJ54LS592W	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8762101FA SNJ54LS592W	Samples
SNJ54LS592W	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8762101FA SNJ54LS592W	Samples
SNJ54LS593J	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS593J	Samples
SNJ54LS593J	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS593J	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.



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PACKAGE OPTION ADDENDUM

13-Aug-2021

⁽⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54LS592, SN54LS593, SN74LS592, SN74LS593 :

- Catalog : SN74LS592, SN74LS593
- Military : SN54LS592, SN54LS593

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS592NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74LS593DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1

TEXAS INSTRUMENTS

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PACKAGE MATERIALS INFORMATION

30-Dec-2020



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS592NSR	SO	NS	16	2000	853.0	449.0	35.0
SN74LS593DWR	SOIC	DW	20	2000	367.0	367.0	45.0

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



4211283-4/E 08/12

D (R-PDSO-G16) PLASTIC SMALL OUTLINE Stencil Openings (Note D) Example Board Layout (Note C) –16x0,55 -14x1,27 -14x1,27 16x1,50 5,40 5.40 Example Non Soldermask Defined Pad Example Pad Geometry (See Note C) 0,60 .55 Example 1. Solder Mask Opening (See Note E) -0,07 All Around

NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0-10 Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



J (R-GDIP-T**) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



- NOTES: A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP2-F16



J (R-GDIP-T**) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



DW0020A



PACKAGE OUTLINE

SOIC - 2.65 mm max height

SOIC



NOTES:

- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M. 2. This drawing is subject to change without notice. 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
- 5. Reference JEDEC registration MS-013.



DW0020A

EXAMPLE BOARD LAYOUT

SOIC - 2.65 mm max height

SOIC



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



DW0020A

EXAMPLE STENCIL DESIGN

SOIC - 2.65 mm max height

SOIC



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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